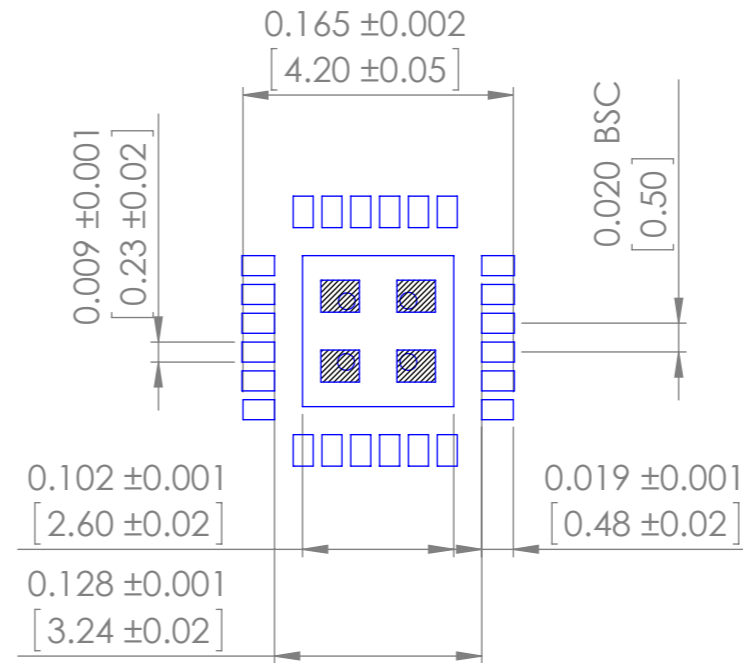
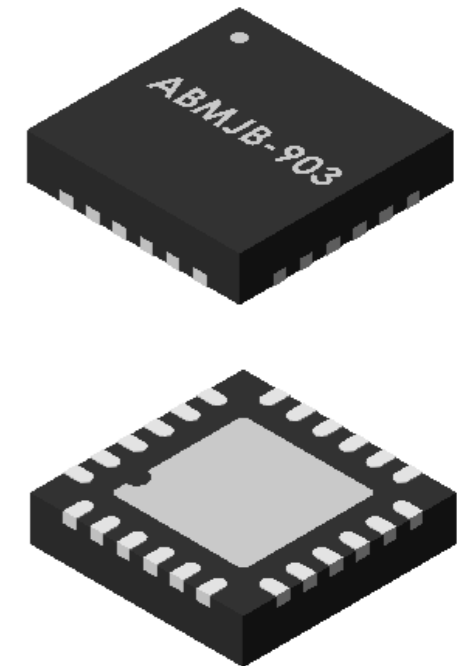


Recommended Land Pattern




| Pin No. | Configuration. |
|---------------------|----------------|
| 22 | Q |
| 23 | /Q |
| 3 | REFIN |
| 12 | OE |
| 1,20 | VDD |
| 17,24 | VDDO |
| 2,8,13,14 15,21 | VSS |
| 4,5,7,9 11,16,18 | DNC |
| 6,10,19 | DNC |
| ePad | Exposed Pad |



Notes:

1. Max Package warpage is 0.05mm.
2. Max allowable burr is 0.076mm in all directions.
3. Pin 1 is on top and will be laser marked.
4. Red circles in land pattern indicate thermal vias. Size should be 0.30-0.35M in diameter and should be connected to GND for max thermal performance.
5. Green rectangles (shaded area) indicate solder stencil opening on exposed pad area. Size should be 1.00 x 1.00 mm in size, 1.20mm pitch.

| | | | | | | |
|--|--------|-----------|-----------------------------------|------------|--|------------|
| UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCH(MM) SURFACE FINISH: TOLERANCES: LINEAR: ANGULAR: | | FINISH: | DEBUR AND BREAK SHARP EDGES | | DO NOT SCALE DRAWING | REVISION - |
| DRAWN - | | SIGNATURE | DATE | |  ABRACON CORPORATION 30332 Esperanza, Rancho Santa margarita, California 92688 | |
| CHK'D | XXXXXX | | | | | |
| APPV'D | | | | | | |
| MFG | | | | | | |
| Q.A | | | | | | |
| | | MATERIAL: | | DWG NO. | ABMJB-903 | |
| | | WEIGHT: | | SCALE:10:1 | SHEET 1 OF 1 | |